

## **BigTwin SuperServer SYS-222BT-HNR-LCC**

2U 4-Node BigTwin with 6 hot-swap 2.5" NVMe drives per node



## **Key Applications**

All-Flash NVMe Hyperconverged Infrastructure, Container-as-a-Service; Application Accelerator, High-Performance File System, Diskless HPC Clusters,

## **Key Features**

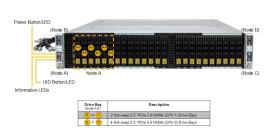
- Four hot-pluggable systems (nodes) in a 2U form factor. Each node supports the following:;
- Dual Socket E2 (LGA-4710) Intel® Xeon® 6700/6500 series processors with Pcores or 6700 series processors with E-cores up to 350W with liquid cooling;
- $\bullet~$  Up to 16 DIMMs supporting up to 4TB DDR5-6400 in 1DPC;
- Flexible networking with up to 1 OCP 3.0 compatible AIOM slots;
- Up to 2 PCle 5.0 x16 LP + 1 PCle 5.0 x16 AIOM slots;
- Up to 6 front hot-swap 2.5" NVMe drive bays;
- 2 Redundant 3600W Titanium Level power supplies;
- 2U Rackmount chassis with 28.75" (730mm) depth;

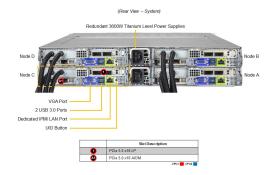


Form Factor	2U Rackmount Enclosure: 449 x 88 x 730mm (17.68" x 3.47" x 28.75") Package: 626 x 248 x 1150mm (24.65" x 9.76" x 45.28")
Processor	Dual Socket E2 (LGA-4710) Intel® Xeon® 6700/6500 series processors with P-cores or 6700 series processors with E-cores P-cores: Up to 86C/172T; Up to 336MB Cache per CPU
System Memory	E-cores: Up to 144C/144T; Up to 108MB Cache per CPU  Slot Count: 16 DIMM slots
	Max Memory (1DPC): Up to 4TB 6400MT/s ECC DDR5 RDIMM
Drive Bays Configuration	Default: Total 6 bays  • 6 front hot-swap 2.5" PCIe 5.0 NVMe drive bays
	M.2: 2 M.2 PCIe 5.0 x4 NVMe slots (M-key 22110(default); VROC required for RAID)
Expansion Slots	Default • 1 PCIe 5.0 x16 LP slot • 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible)
	Option A • 2 PCIe 5.0 x16 LP slots • 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible)
On-Board Devices	Chipset: System on Chip Network Connectivity: Via AIOM
Input / Output	LAN: 1 RJ45 1 GbE Dedicated BMC LAN port USB: 2 USB 3.0 Gen2 Type-A ports(Rear) Video: 1 VGA port



(Front View - System)





System Cooling	Fans: 4x 16K RPM Counter Rotating 80x80x56mm Fan(s) Air Shroud: 4 Air Shrouds Liquid Cooling: Direct to Chip (D2C) Cold Plate
Power Supply	2x 3600W Redundant (1 + 1) Titanium Level (96%) power supplies
System BIOS	BIOS Type: AMI 32MB Flash ROM
Management	SuperCloud Composer®; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); SuperServer Automation Assistant (SAA) New!
PC Health Monitoring	FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment CPU: Monitors for CPU Cores, Chipset Voltages, Memory. 8+4 Phase-switching voltage regulator
Dimensions and Weight	Weight: Gross Weight: 96.6 lbs (43.8 kg)  Net Weight: 66.1 lbs (30 kg)  Available Color: Black front & silver body
Operating Environment	RoHS Compliant Operating Temperature: 10°C to 35°C (50°F to 95°F) Non-operating Temperature: -30°C to 60°C (-22°F to 140°F) Operating Relative Humidity: 8% to 80% (non-condensing) Non-operating Relative Humidity: 8% to 90% (non-condensing)
Motherboard	Super X14DBT-B
Chassis	CSE-217BQ2-R3K60P